IPC ASSOCIATION COI ELECTRONICS INI	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfc Information				
upplier In	nformation													
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*			
nsemi											2024-05-15			
Contact Name	e	Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized R	epresentative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	ı	Manufacturing Site		eight*	UOM	Unit Type
		SURA8205T3G-GA01 Auto Standard SU		RA8205T3G		2024-05-15 CNP		62	.01	mg	Each			
Ianufactu	ring Proccess Inform	ation						·						
Terminal Plating / Grid Array Material Terminal Base			Terminal Base A	al Base Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak T				Temperature Number of Reflow Cycles			
Ma	atte Tin (Sn) - annealed	C	CU Alloy	1			260		C	30	seconds	3		
omments														
vel 1 - maxii	mum time at peak tempera	ture during sol	ldering is 10-3	0 seconds										
or more info	ormation regarding materia	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.0	mg	Supplier	Iron (Fe)	7439-89-6		0.006	mg
			Supplier	Copper (Cu)	7440-50-8		5.9922	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0018	mg
Die	0.84	mg	Supplier	Silicon (Si)	7440-21-3		0.8316	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0084	mg
Die Attach Solder	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.073	mg
			A	Lead (Pb)	7439-92-1	7a	2.701	mg
			Supplier	Tin (Sn)	7440-31-5		0.146	mg
Lead Frame	22.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0226	mg
			Supplier	Copper (Cu)	7440-50-8		22.6006	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0068	mg
Mold Compound-Black	29.54		Supplier	Polycondensate of 4,4'-bis(methoxymethyl)biphenyl and phenol	205830-20-2		0.7385	mg
			Supplier	Triphenylphosphine	603-35-0		0.1477	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.1477	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1477	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2954	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.586	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.477	mg
Plating	0.08	mg	Supplier	Tin (Sn)	7440-31-5		0.08	mg